

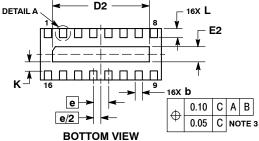
WDFN16, 4x1.7, 0.5P

DATE 21 JUL 2010

NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30 MM FROM TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.70	0.80	
A1	0.00	0.05	
АЗ	0.20 REF		
b	0.20	0.30	
D	4.00 BSC		
D2	3.10	3.30	
Е	1.70 BSC		
E2	0.40	0.60	
е	0.50 BSC		
K	0.30 REF		
L	0.25	0.35	
L1		0.15	



RECOMMENDED SOLDERING FOOTPRINT* 16X ⊢0.53 2.00 0.60 16X 0.30 0.50 **PITCH DIMENSION: MILLIMETERS**

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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